

Chip Design

Tools, Technologies & Methodologies

Chip Design Marketing and Lead Generation Programs Connect You with Real Buyers in the Advanced IC Design Market

Learn why IR cameras are crucial for micro-electronic quality control

Chip Design
Tools, Technologies & Methodologies

HOME | SYSTEMS DESIGN | LOW POWER | SOLID STATE | FPGA | RF | MEMS | IC | MULTICORE | MAGAZINE | NEWSLETTERS | BLOGS | VIDEOS | FEATURED SOLUTIONS

Featured White Papers

- Interview with Pim Tuyls, President and CEO of Intrinsic-ID**
Continuing the coverage on security here is the opinion from Intrinsic-ID
[read more](#)
- Small Becomes a Bigger Deal**
A processor designed from the ground up for tough phone makes a difference for industrial and on-earbuds (Apple iW-ultra, Intel, 122M alpha+algos) will
[read more](#)
- When It Comes to Gaming, Embedded GPUs are No Gamble**
Gaming laptops vendors and partners must understand the implications of hardware that is implemented in their gaming machines. Electronic gaming
[read more](#)
- USB Learning Curve Gets a Little Steeper, But Resources Are Out There**
Whether you need expert opinion on a schematic, feedback from a certification workshop, or want to know more about ergonomic considerations,
[read more](#)

IP INTEGRATION MARKET SURVEY
IPDesigner & Integrator
Share your IP integration experiences
Win \$100 gift card + an executive summary of the report
[Begin survey now](#)

VIEW THE WEBINAR VIDEO
Try IP before you buy: Real-time PPA analysis from eSilicon
Get immediate answers to your power, performance or area (PPA) questions on eSilicon's memory compilers and VPO using the IP MarketPlace™ environment (no cost or obligation). Demo video is now available. Recorded January 21, 2015.
Sponsored by: **eSilicon**

BLOGS - Gabe's EDA
Interview with Pim Tuyls, President and CEO of Intrinsic-ID
Leon Merrill, Senior Editor asks the articles on security published last week, I confirmed the coverable with him.
IC Design
Context-Aware Latch-up

NEWS, ANALYSIS & FEATURES

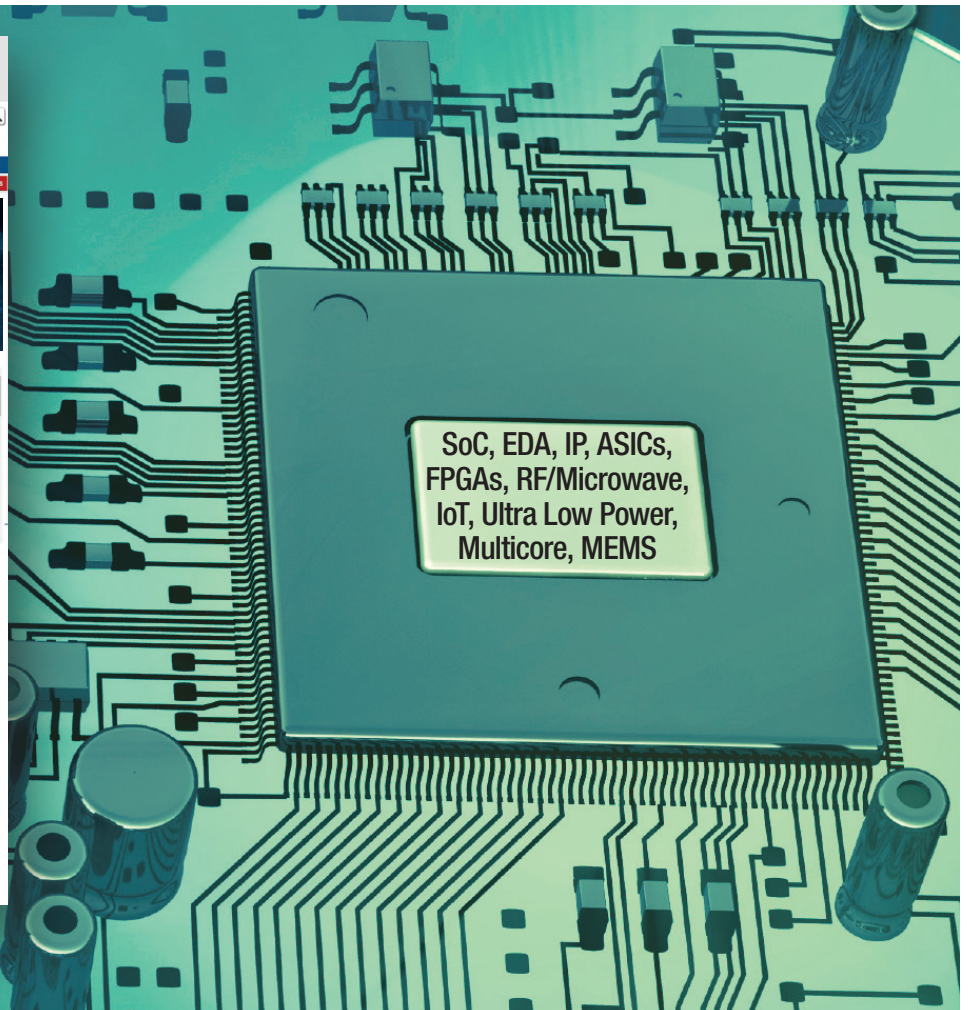
- ARM TechCon: uniting the design community**
Uniting hardware and software engineers in an event that offers an expo, conference and training. [ARM](#)
- Anritsu MT8212C First Single-Instrument Solution to Support LTE-A 4x4 MIMO, 200k Evaluation ...**
Release of LTE 4x4 MIMO DL and LTE-Advanced DL CA SDCs Measurement Software Packages Expand Industry-leading ...
- ADLINK Announces New Release 3.5 of SEMA Intelligent Middleware for Monitoring, Control ...**
New version of SEMA offers a broad spectrum of enhanced functionality to improve system reliability ...
- Simplifying Power Management for MCU-Based IoT Nodes**
More IoT apps, more battery-powered connected sensors and actuators. And more time for silicon ...
- ARM enables autonomous vehicles with its most advanced safety processor**
The ARM Cortex-R52 meets the highest functional safety standards. Delivers the robust, real-time ...
- STMicroelectronics and Witlicity to Develop Integrated Circuits (ICs) for Resonant Wireless ...**
Chips to accelerate the adoption of wireless charging, with ability to efficiently charge metal-body ...
- CEL Launches Comet IoT Industrial Wireless Connectivity Platform**
CEL Adds Voice Control and Solves the Network Latency Problem for Large Scale Lighting and Industrial ...
- Interview with Pim Tuyls, President and CEO of Intrinsic-ID**
Continuing the coverage on security here is the opinion from Intrinsic-ID
[read more](#)
- Mercury Systems Introduces the First Secure Rackmount Server for the Defense Market**
New line of rugged servers ideal for mission, sensor processing and cybersecurity applications Building ...
- Silicon Labs acquires leading RTO's company Micrium**
Silicon Labs (NASDAQ: SLAB) today announced the acquisition of

NEW WHITE PAPERS

Ultra PLL
Ultra low jitter performance
Ultra wide multiplication range
Precise frequency control
Optimal spread spectrum
[Learn more](#)

FPGA Prototyping Bridges Global Design
[Clarifying Embedded IoT Connections](#)
[Highlights include Si-based mole...](#)

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The largest, most qualified community of design engineers and engineering managers working on advanced SoC designs

Informing Chip and SoC design decision makers with unparalleled technology and business insights



PETE SINGER
Editorial Director & Associate Publisher

Pete oversees the editorial operations of Chip Design, Solid State Technology and The ConFab. He has been involved in technical journalism for more than 30 years and has written over 150 articles on all aspects of semiconductor manufacturing and design industries.



GABE MORETTI
Senior Editor

Gabe Moretti has been in EDA for over 40 years. The first 31 were spent in engineering activities, developing EDA tools and participating in IEEE standards making activities.



CAROLINE HAYES
Senior Editor

Caroline Hayes has been a journalist, covering the electronics sector for over 20 years. She has worked on many titles, most recently the pan-European magazine, EPN.



CHRIS CIUFFO
Senior Editor

Chris is Senior Editor for embedded content for *Embedded Systems*

Engineering, *EECatalog*, and *Embedded Intel® Solutions*. He has 30 years of embedded technology experience with degrees in electrical engineering and materials science.



TERRY COSTLOW
News Editor

Terry Costlow covers the electronics industry, examining the interplay between technology and business. He's contributed regularly

to *Electronic Engineering Times*, *Automotive Engineering International*, *Automation World*, *Design News* and *IEEE Spectrum*. He's also written for consumer publications including *The Christian Science Monitor*, *Los Angeles Magazine* and the *Portland Oregonian*.

Chip Design's convenient email newsletters, content-rich websites, and annual publication (releasing at DAC) are seen by **more than 120,000 engineering and management professionals in 101 countries** each month.

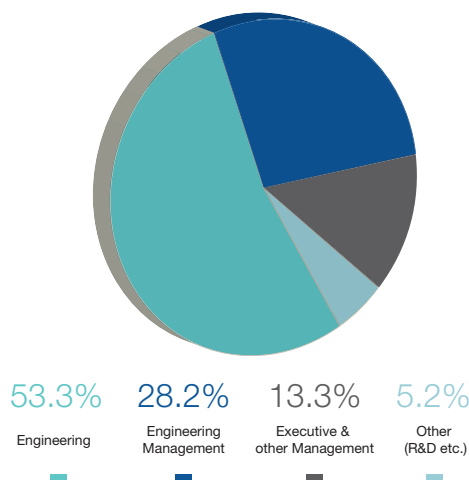
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- **www.ChipDesignMag.com:** Purchase influencers research suppliers and products online using Chip Design's informative articles, video library, news, research, white papers, and featured solutions guide. **Average session is over 44 minutes!**
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- **Email Newsletters:** Design engineers and engineering managers working on advanced SoC designs stay informed by reading *Chip Designer*, *IP Designer & Integrator* and *RF & Microwave Systems* for important industry news, product information, research, videos and more.
- **Events:** Semiconductor design and manufacturing industry leaders gather each year at **The Confab** to connect, collaborate and create the future. IoT Executives gather each year at the **Internet of Things Developers Conference**.

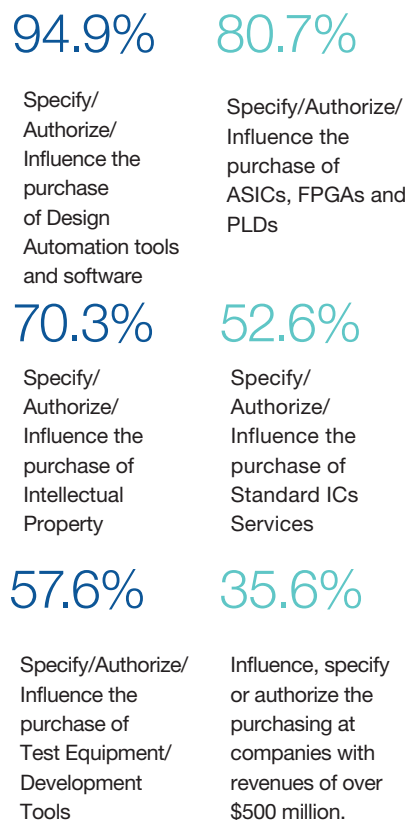
Audience Demographics

System architect, design and test engineers and engineering managers working on advanced SoC designs—Chip Design readers—account for a third of all design engineers. These key enablers influence the purchase of nearly 80% of the total EDA market.

Circulation by Job Responsibility



Circulation breakdown by Purchasing Responsibility



Top 30 Subscribing Companies

- | | | |
|-----------------|--------------------|---------------------|
| Altera | IBM | ON Semiconductor |
| AMD | IDT | Oracle |
| Analog Devices | Infineon | PMC-Sierra |
| Atmel | Intel | Qualcomm |
| Broadcom | Hewlett-Packard | Rohm Semiconductor |
| Cypress | LSI | Samsung Electronics |
| Cisco | Marvell | ST Microelectronics |
| Freescale | Maxim Integrated | Texas Instruments |
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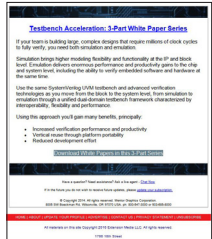
“Spotlight On” Position
(limited to 2 companies)
 High impact and above the fold
 Price - \$1,950 per month

Video Program:
 \$1,000; \$2,500 for
 editorial interview

Banners

- Leaderboard (728x90) - \$100 cpm
- Large Rectangle (336x280) - \$100 cpm
- Half Page(300x600) - \$100 cpm
- Welcome Page (800x600) - \$450 cpm
- Exclusive “Push Down” Banner - High Impact banner expands to a maximum of 970 x 418 and then retracts to 970 x 90

Lead Generation



Dedicated Email Blasts
 Generate powerful leads with Chip Design Dedicated Email Blasts

- \$250 cpm
- 15,000 minimum list size

Technology Paper Sponsorship - Featured on the Chip Design site for 3 months as a PDF

- Featured on Chip Design website for 3 months

- Links to your registration form or use our registration form to collect downloaders' contact information. We collect leads - additional \$500
- Featured in 3 issues of Chip Designer e-Newsletter & Monthly White Paper Resource Newsletter distributed to over 50,000 subscribers.
- **\$1,000** (online only)
- **\$2,950** (includes online, and dedicated email blast to 25,000)

Chip Design's Platinum Marketing Membership (Includes Social Media Marketing!)

- Banner Impressions – 5,000 impressions each month
- One Gold or Silver Sponsorship of *Chip Designer* or *IP Designer & Integrator* newsletter per quarter or an additional 2,500 banner impressions
- Posting of your message to our social media pages (nearly 4,000 Facebook and 1,000+ twitter follows and growing!)
- Unlimited press releases
- One online Product Showcase
- Feature 1 video or 1 white paper online
- 1 Dedicated email blast every 6 months – 15,000 (add-on)

Price: \$950 per month – 6 month program (\$1,250 per month/with email blast add-on/6 month program)

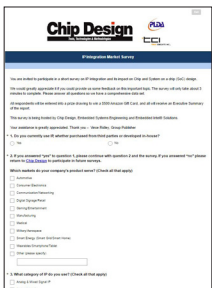
Email Newsletters



Chip Designer e-Newsletter (Bi-monthly): 45,000 Subscribers
IP Designer – Integrator e-Newsletter (Monthly): 33,000 Subscribers
RF & Microwave Systems e-newsletter (Quarterly): 30,000 Subscribers
FPGA & CPLD Quarterly Update e-newsletter: 36,000 Subscribers

Platinum Sponsor - Exclusive
 468x90 banner at top center position and first text ad - \$1,500/issue
Gold Sponsor - Exclusive
 Skyscraper top right banner position and second text ad - \$1,250/issue
Silver Sponsor - Exclusive
 Second/third from top 125 x 125 banner position and third/fourth text ad - \$1,000/issue

Market Surveys: The Most Powerful Lead Generation Tool



Chip Design conducts Market Intelligence Survey of its readership. Data collected includes industry trends, buying preferences, key factors influencing purchasing and much more including contact data on all respondents.

Custom surveys also available upon request

Sponsorship net rate: \$3,500 (sponsor may add 2 proprietary questions at an additional fee of \$2,500 per program) Sign-up for all 4 surveys for \$9,500

2016 Market Intelligence/Lead Generation Topics

- EDA Tech & Tools – Feb.
- Available for Custom Survey - April
- Verification – June
- Available for Custom Survey - Sept.
- EDA Tech & Tools – Oct.

CHIPDESIGNMAG.COM

Avg. Monthly Page Views: 237,598
 Page Visits: 44,053
 Avg. Time on Site: 44:31

► DAC Special Offers

Magazine Incentives

Advertisers in the DAC show issue receive:

- **FREE Resource Guide Product Showcase FREE in the DAC issue and online for 12 months**

Video Showcase Program

- Promote a new product or announcement on camera at DAC
- Your video will be recorded at the event then posted on the Chip Design website and promoted in six issues of Chip Designer to more than 40,000 SoC Designer decision makers
- PLUS, you receive a copy of the video to post on your site or YouTube and use for other marketing efforts
- Net rate \$1,750; \$2,500 for editorial interview

Product Showcase Newsletter - 35,000 Subscribers

Get exposure for your products, drive traffic to your booth and reach those unable to attend the show with a listing in the Product Showcase e-Newsletter.

- Product Listing: \$750
- Leaderboard - \$1,500 net
- Skyscraper on right rail - \$1,500 net
- Silver (125x125) - \$750 net (limited availability)

DAC E-Daily - 35,000 Subscribers

Leverage Chip Design's DAC coverage by positioning your advertising in our special e-Show Daily e-Newsletter and on ChipDesignMag.com distributed daily during DAC (June 8-10). The daily newsletter goes out to over 35,000 subscribers.

Platinum	\$2,000
Gold	\$1,500
Silver #1	\$1,000
Silver #2	\$1,000
Silver #3	\$1,000

Participate in the May 2017 Chip Design Webcast: “Chip Design for the Internet of Things”
 Sponsor Fee: \$2,500

Don't Miss Out on these Face to Face Opportunities



May 14-17, 2017 | Hotel del Coronado | San Diego, CA

Attendee Profile: Sponsors of The ConFab gain the unique opportunity to meet with a verified group of influential executives involved in buying the total spectrum of products, materials and services involved in semiconductor manufacturing and design.



April 26-27, 2017 | Santa Clara Convention Center | Santa Clara

- The Biggest and most important IoT conference of the year dedicated to IoT technology in Semiconductor Design & Embedded Systems
- 1,500 Pre-qualified attendees in 2016



Co-located with Internet of Things Developers Conference

Dedicated to the implementation of machine learning and artificial intelligence technologies.

2017 Editorial Calendar

	MAGAZINE	FOCUS REPORTS	MARKET RESEARCH	E-NEWSLETTERS					
	Magazine Topics	Bonus Distribution	Lead Generation	Chip Designer	IP Designer & Integration	FPGA & PLD Quarterly Report	Sensors & MEMS Quarterly Report	RF & Microwave Systems Qtrly.	
WINTER/SPRING			EDA Tech & Tools One Custom Survey	Jan. 18 Feb. 22 Mar. 22 Apr. 19 May 24	Jan. 11 Feb. 15 Mar. 15 Apr. 12 May 17	Feb. 9 May 18	Jan. 12 April 12	Feb. 2 May 4	
RF AND MICROWAVE SYSTEM	Ad Close: April 6 Material: April 10 Wearable Electronics and RF/Microwave for IoT RF/Microwave IP Telecommunications RFID Packaging Considerations Testing Beyond 40 GHz	IMS 2017 DAC Mobile World Congress Americas 2017 (San Francisco)		Special Issue Sponsored by IMS 2017					
SUMMER/FALL ISSUE	Ad Close: May 14 Material: May 16 Designing Sub-10nm ICs Design Troubleshooting: Analysis and Debugging Tools Design Automation for the IoT Chip-Package-Board Co-Design Power, Performance, Area (PPA) Optimization Understanding Giga-Scale Challenges	DAC (San Francisco, CA) Semicon West (San Francisco, CA)	Annual Resource Guide	Verification One Custom Survey EDA Tech & Tools Webcast Chip Design for the Internet of Things	June 21 July 19 Aug. 23 Sept. 20 Oct. 25 Nov. 15 Dec. 13	June 14 July 12 Aug. 16 Sept. 13 Oct. 18 Nov. 8 Dec. 6	Aug. 17 Nov. 9	July 13 Oct. 12	Aug. 3 Nov. 2

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Chip Design Magazine & Engineers' Guides focused on specific markets (FPGA's; RF and Microwave; Sensors & MEMs)

- Engineers' Guide to FPGA & PLD - 40,000 qualified subscribers
- Engineers' Guide to Sensors & MEMs - 40,000 qualified subscribers
- RF & Microwave Systems - 32,500 qualified subscribers

Bonus Distribution: DAC, DesignCon, ARM TechCon, DVCon, Semicon West, Embedded World, IoT DevCon, Embedded Systems Conference

Magazine Net Rate

Two-page Spread	\$3,950
Full Page	\$2,500
Half Page	\$1,750
Back Cover	\$4,000
Inside Back Cover	\$3,500
Inside Front Cover Spread	\$3,750
Page 1	\$3,500

Product Showcase Rates

Full Page Product Showcase	\$1,250
(additional products 50% off)	
1/2 page Product Showcase	Net Rate: \$950
(additional products 35% off)	

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